

PLANARIZING COATING PC3-700

Description

- The main application of PC3-700 is the large area planarization of surface topology. PC3-700 is etched back to transfer the planarity of PC3-700 to the underlying dielectric.
- These are the advantages of PC3-700 over other products:
 - superior planarizing capability in comparison to any photoresist
 - outstanding etchback compatibility with underlying dielectric
- The formulation and processing of PC3-700 were designed with regard to occupational and environmental safety. The principal solvent in PC3-700 is n-butyl acetate.

Properties

◆ Solids content (%)	32-34
◆ Principal solvent	n-butyl acetate
◆ Appearance	reddish brown liquid
◆ Coating characteristic	very uniform, striation free
◆ Film thickness after 200°C hotplate bake for 120 s. <u>Coating spin speed, 40 s spin (rpm):</u>	(nm)
800	1250-1550
3000	600-800
◆ Guaranteed shelf life at 25°C storage (years)	2

Process Application

1. Spin coating of a substrate with PC3-700 at a selected spin speed for 40 s. Application of adhesion promoters is not recommended.
2. 200°C bake on a hot plate for 120 s.
3. RIE etchback process.